SiHF12N65E

Vishay Siliconix



PRODUCT SUMMARY

V_{DS} (V) at T_J max.

Q_q max. (nC)

Configuration

Q_{gs} (nC) Q_{gd} (nC)

R_{DS(on)} max. (Ω) at 25 °C

GDS

TO-220 FULLPAK

E Series Power MOSFET

S

N-Channel MOSFET

0.38

700

70

9

16

Single

V_{GS} = 10 V



- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220 FULLPAK
Lead (Pb)-free and Halogen-free	SiHF12N65E-GE3

ABSOLUTE MAXIMUM RATINGS (T C	= 25 °C, unl	less otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	650	v	
Gate-Source Voltage			V _{GS}	± 30	v	
Continuous Drain Current (T _J = 150 °C) e	V _{GS} at 10 V	$T_{\rm C} = 25 \ ^{\circ}{\rm C}$ $T_{\rm C} = 100 \ ^{\circ}{\rm C}$	Ι _D	12		
	V _{GS} at 10 V	T _C = 100 °C		8	А	
Pulsed Drain Current ^a			I _{DM}	28		
Linear Derating Factor				0.26	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	226	mJ	
Maximum Power Dissipation			PD	33	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C		
Drain-Source Voltage Slope	T _J = 125 °C		dV/dt	37	V/ns	
Reverse Diode dV/dt ^d		uv/ut	28	v/11S		
Soldering Recommendations (Peak temperature) ^c	For 10 s			300	°C	
Mounting Torque	M3 screw			0.6	Nm	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 4 A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D, \, dI/dt$ = 100 A/µs, starting T_J = 25 °C.

e. Limited by maximum junction temperature.

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1 For technical questions, contact: <u>hvm@vishay.com</u>

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PARAMETER	SYMBOL	TYP.		MAX.			UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-		65				
Maximum Junction-to-Case (Drain)	R _{thJC}	- 3.8				°C/W		
SPECIFICATIONS ($T_J = 25 \text{ °C}, u$	nless otherw	ise noted)						
PARAMETER	SYMBOL	TES		ONS	MIN.	TYP.	MAX.	UNI
Static								
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 2	250 μA	650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	l _D = 1 mA	-	0.78	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 2	250 μA	2	-	4	V
Gate-Source Leakage	lass	$V_{GS} = \pm 20 V$		-	-	± 100	nA	
Gale-Source Leakage	I _{GSS}		$V_{GS} = \pm 30 \text{ V}$		-	-	± 1	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =	$V_{DS} = 650 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			-	1	μA
		V _{DS} = 520 V	$V_{DS} = 520 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			-	10	
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	l	_D = 6 A	-	0.33	0.38	Ω
Forward Transconductance	g _{fs}	V _{DS}	= 30 V, I _D =	= 6 A	-	3.5	-	S
Dynamic						•	•	
Input Capacitance	C _{iss}	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ $f = 1 MHz$ $V_{DS} = 0 V \text{ to } 520 V, V_{GS} = 0 V$		-	1224	-	pF	
Output Capacitance	C _{oss}			-	65	-		
Reverse Transfer Capacitance	C _{rss}			-	4	-		
Effective Output Capacitance, Energy Related ^a	C _{o(er)}			-	50	-		
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	160	-		
Total Gate Charge	Qg				-	35	70	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V I _D = 6 A, V _{DS} = 520 V		-	9	-	nC	
Gate-Drain Charge	Q _{gd}				-	16	-	1
Turn-On Delay Time	t _{d(on)}	$V_{DD} = 520 \text{ V}, \text{ I}_{D} = 6 \text{ A},$ $V_{GS} = 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$		-	16	32	- ns	
Rise Time	t _r			-	19	38		
Turn-Off Delay Time	t _{d(off)}			-	35	70		
Fall Time	t _f			-	18	36		
Gate Input Resistance	Rg	f = 1 MHz, open drain		-	0.81	-	Ω	
Drain-Source Body Diode Characteristic								
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	MOSFET symbol showing the		-	-	12	
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	28	A	
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 6 A, V _{GS} = 0 V		-	1.0	1.2	V	
Reverse Recovery Time	t _{rr}	$T_{J} = 25 \text{ °C}, I_{F} = I_{S} = 6 \text{ A},$ $dI/dt = 100 \text{ A}/\mu\text{s}, V_{R} = 25 \text{ V}$		-	309	618	ns	
Reverse Recovery Charge	Q _{rr}			-	3.8	7.6	μΟ	
Reverse Recovery Current	I _{RRM}			-	21	-	A	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

b. Coss(tr) is a fixed capacitance that gives the same charging time as Coss while VDS is rising from 0 % to 80 % VDSS.



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

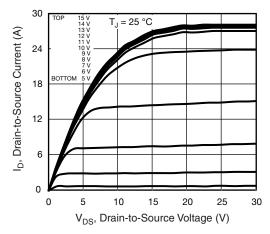


Fig. 1 - Typical Output Characteristics

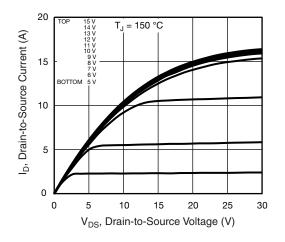


Fig. 2 - Typical Output Characteristics

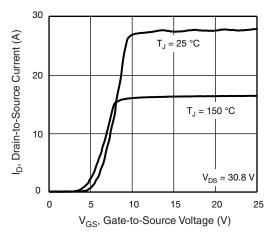


Fig. 3 - Typical Transfer Characteristics

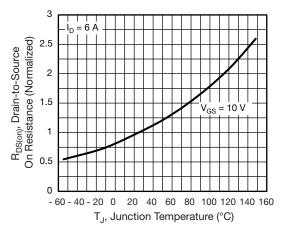


Fig. 4 - Normalized On-Resistance vs. Temperature

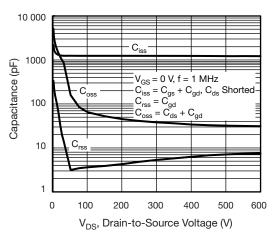


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

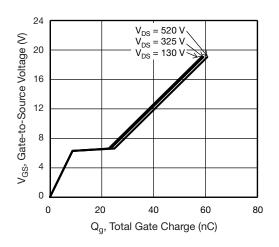


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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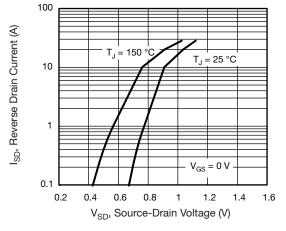


Fig. 7 - Typical Source-Drain Diode Forward Voltage

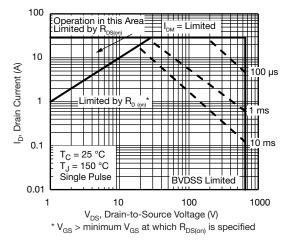


Fig. 8 - Maximum Safe Operating Area

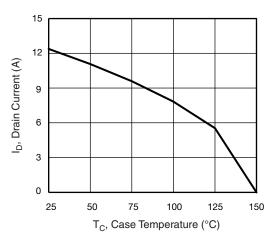


Fig. 9 - Maximum Drain Current vs. Case Temperature

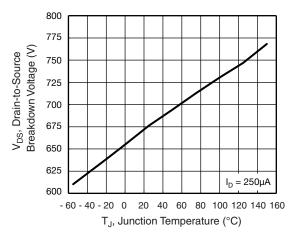
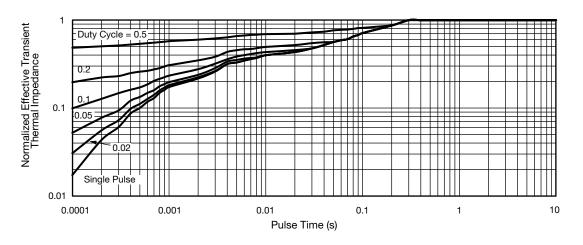


Fig. 10 - Temperature vs. Drain-to-Source Voltage





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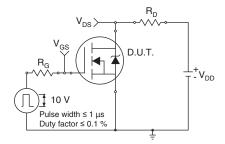


Fig. 12 - Switching Time Test Circuit

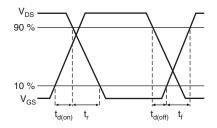


Fig. 13 - Switching Time Waveforms

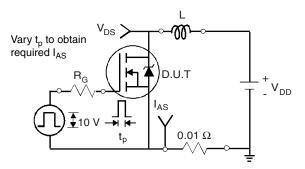


Fig. 14 - Unclamped Inductive Test Circuit

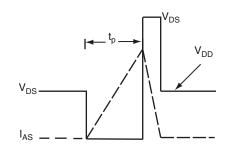


Fig. 15 - Unclamped Inductive Waveforms

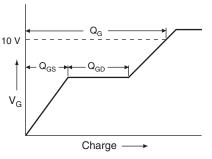


Fig. 16 - Basic Gate Charge Waveform

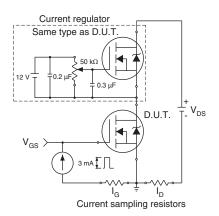


Fig. 17 - Gate Charge Test Circuit



SHAY

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Peak Diode Recovery dV/dt Test Circuit

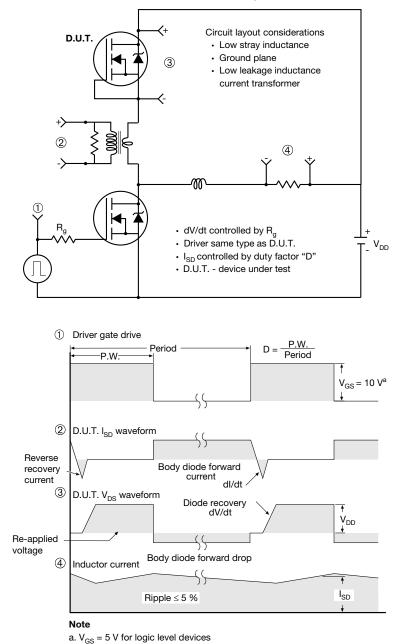


Fig. 18 - For N-Channel

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